

1.6x0.6mm RIGHT ANGLE SMD CHIP LED **LAMP**

Part Number: APA1606MGC

Mega Green

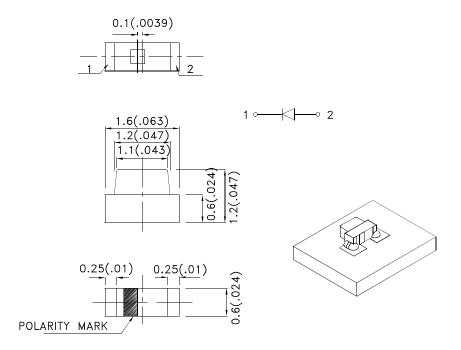
Features

- 1.6mmx0.6mm right angle SMT LED,1.2mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package :2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Mega Green source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		21	Min.	Тур.	201/2
APA1606MGC	Mega Green (AlGaInP)	WATER CLEAR	36	80	110°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Mega Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	IF=20mA
С	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA
lR	Reverse Current	Mega Green		10	uA	V _R =5V

- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

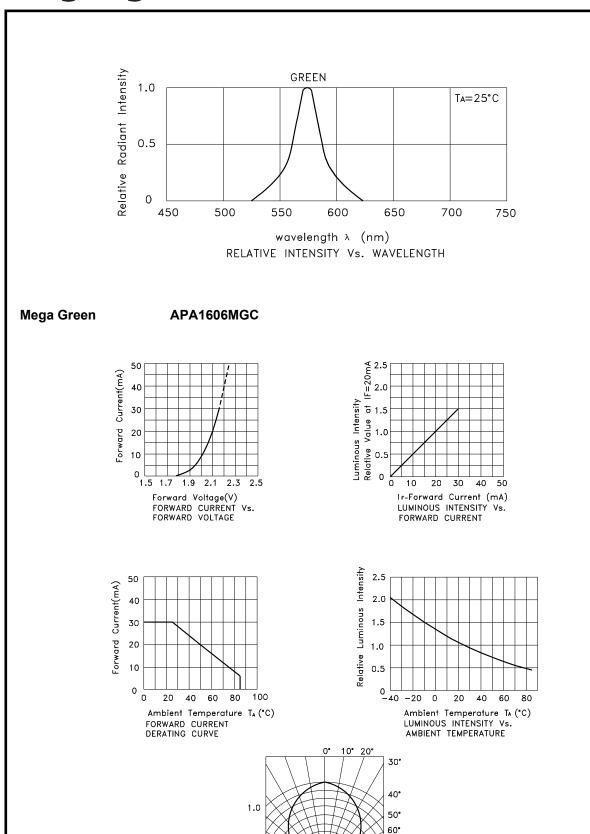
Absolute Maximum Ratings at TA=25°C

Parameter	Mega Green	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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SPATIAL DISTRIBUTION

0.7

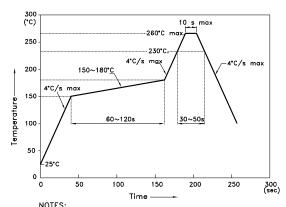
70° 80°

90°

APA1606MGC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



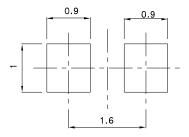
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

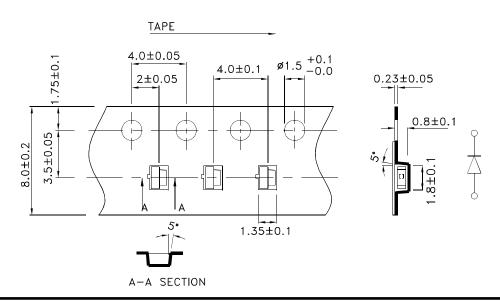
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. to high temperature.

 3.Number of reflow process shall be 2 times or less.

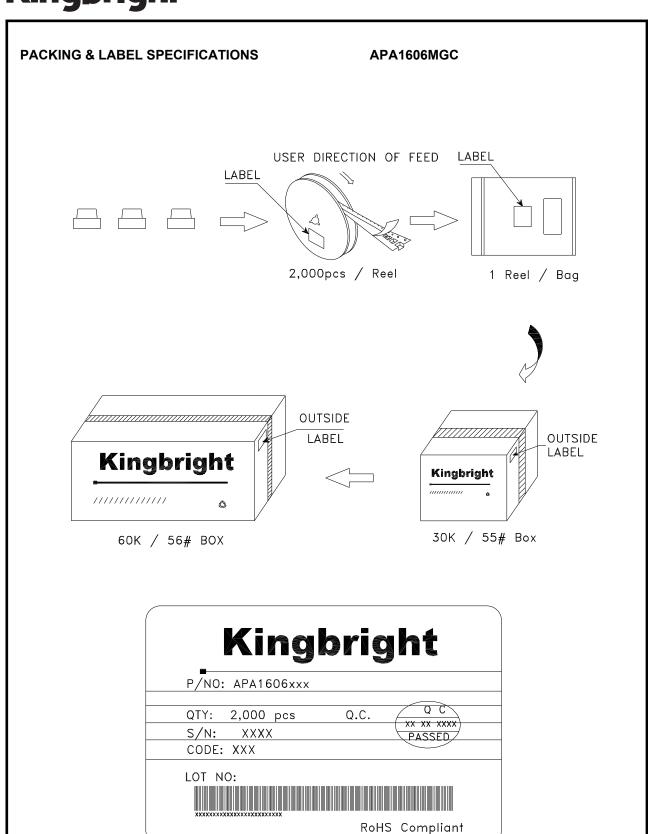
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)



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